Vishay Siliconix

P-Channel 30 V (D-S) MOSFET

SOT-23 (TO-236) D 3 2 S

Marking code: G6

PRODUCT SUMMARY					
V _{DS} (V)	-30				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.0227				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5 \text{ V}$	0.0330				
Q _g typ. (nC)	8.2				
I _D (A) ^{a, e}	-7.5				
Configuration	Single				

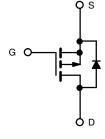
FEATURES

- TrenchFET® Gen IV p-channel power MOSFET
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



APPLICATIONS

- · Load switch
- Circuit protection
- · Motor drive control



P-Channel MOSFET

ORDERING INFORMATION				
Package	SOT-23			
Lead (Pb)-free and halogen-free	Si2393DS-T1-GE3			

PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	-30	V
Gate-source voltage		V _{GS}	-20 / +16	V
	T _C = 25 °C		-7.5 ^e	
Continuous drain surrent (T = 150 °C)	T _C = 70 °C		-6.9	
Continuous drain current (T _J = 150 °C)	T _A = 25 °C	I _D	-6.1 ^{b, c}	
	T _A = 70 °C		-4.8 ^{b, c}	А
Pulsed drain current (t = 100 μs)		I _{DM}	-50	
Continuous source-drain diode current	T _C = 25 °C		-2.1	
	T _A = 25 °C	l _s	-1.1 ^{b, c}	
Maximum power dissipation	T _C = 25 °C		2.5	
	T _C = 70 °C		1.6	w
	T _A = 25 °C	P _D	1.3 ^{b, c}	
	T _A = 70 °C		0.8 b, c	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C

THERMAL RESISTANCE RATINGS							
PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT			
Maximum junction-to-ambient ^b	t ≤ 5 s	R _{thJA}	75	100	°C/W		
Maximum junction-to-case (drain)	Steady state	R_{thJF}	40	50			

Notes

- a. Based on $T_C = 25\ ^{\circ}C$
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 5 s
- d. Maximum under steady state conditions is 166 °C/W
- e. Package limited



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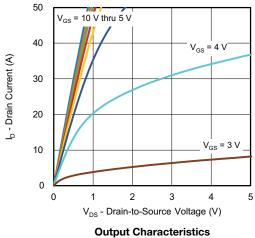
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-30	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = -250 μA	-	-24.7	-	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	-	5.7	-	mV/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	-1	-	-2.2	V
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = -20 \text{ V} / +16 \text{ V}$	-	-	100	nA
		V _{DS} = -30 V, V _{GS} = 0 V	-	=	-1	μA
Zero gate voltage drain current	I _{DSS}	V _{DS} = -30 V, V _{GS} = 0 V, T _J = 70 °C	-	=	-15	
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -10 \text{ V}$	-10	-	-	Α
	_ ` ′	V _{GS} = -10 V, I _D = -5 A	-	0.0189	0.0227	
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = -4.5 \text{ V}, I_D = -3 \text{ A}$	-	0.0264	0.0330	Ω
Forward transconductance ^a	9 _{fs}	V _{DS} = -15 V, I _D = -5 A	-	10	-	S
Dynamic ^b						
Input capacitance	C _{iss}		-	980	-	pF
Output capacitance	Coss	$V_{DS} = -15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	440	-	
Reverse transfer capacitance	C _{rss}		-	55	-	
Total gate charge	Qg	V _{DS} = -15 V, V _{GS} = -10 V, I _D = -6.1 A	-	16.8	25.2	nC
			-	8.2	12.3	
Gate-source charge	Q _{gs}	V _{DS} = -15 V, V _{GS} = -4.5 V, I _D =-6.1 A	-	3.6	-	
Gate-drain charge	Q _{ad}		-	2.8	-	
Gate resistance	R _g	f = 1 MHz	3.6	18.3	36.6	Ω
Turn-on delay time	t _{d(on)}		-	14	28	
Rise time	t _r	$V_{DD} = -15 \text{ V}, R_L = 2.5 \Omega, I_D \cong -4.8 \text{ A},$	-	8	16	1
Turn-off delay time	t _{d(off)}	$V_{GEN} = -10 \text{ V}, R_g = 1 \Omega$	-	48	96	
Fall time	t _f		-	32	64	1
Turn-on delay time	t _{d(on)}		-	30	45	ns
Rise time	t _r	$V_{DD} = -15 \text{ V}, R_L = 2.5 \Omega, I_D \cong -4.8 \text{ A},$	-	85	170	
Turn-off delay time	t _{d(off)}	$V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$	-	34	68	1
Fall time	t _f	-	-	40	80	1
Drain-Source Body Diode Characteristi					1	
Continuous source-drain diode current	Is	T _C = 25 °C	_	-	-2.1	
Pulse diode forward current	I _{SM}	-	-	-	-50	A
Body diode voltage	V _{SD}	I _S = -4.8 A, V _{GS} = 0 V	-	-0.8	-1.2	V
Body diode reverse recovery time	t _{rr}	3 / 40 -	-	21	42	ns
Body diode reverse recovery charge	Q _{rr}	I _F = -4.8 A, di/dt = 100 A/μs,	_	8	16	nC
Reverse recovery fall time	t _a	$T_{\rm J} = 25 ^{\circ}{\rm C}$	-	8.5	-	
Reverse recovery rise time	t _b	-	_	12.5	<u> </u>	ns

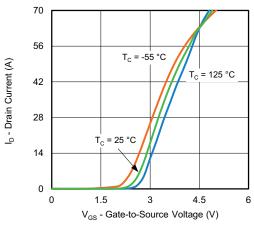
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

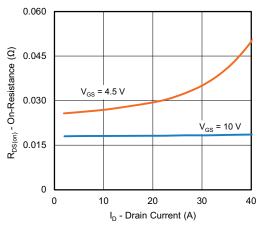


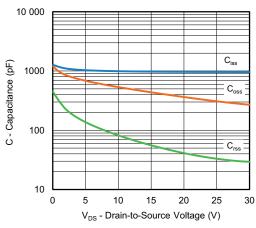






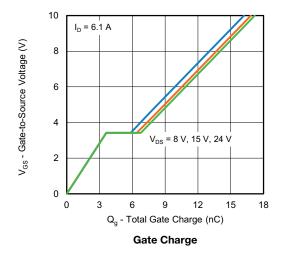


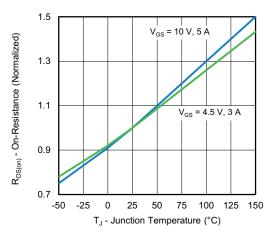




On-Resistance vs. Drain Current and Gate Voltage

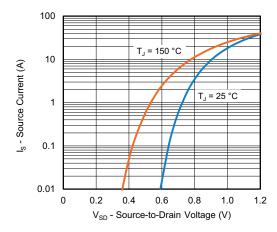
Capacitance



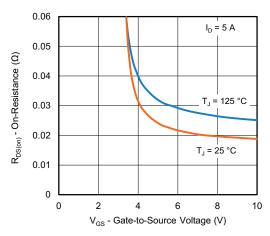


On-Resistance vs. Junction Temperature

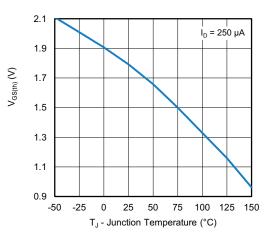




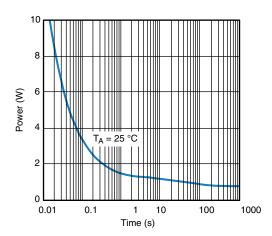
Source-Drain Diode Forward Voltage



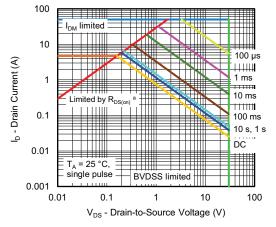
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



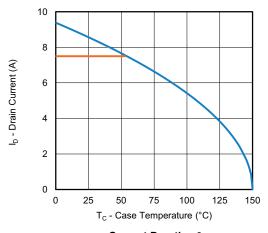
Single Pulse Power, Junction-to-Ambient



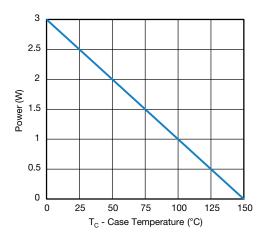
Safe Operating Area, Junction-to-Ambient

Note

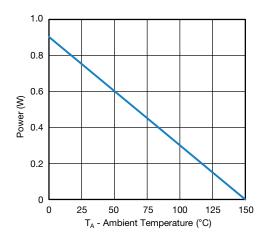
a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified



Current Derating a



Power, Junction-to-Case

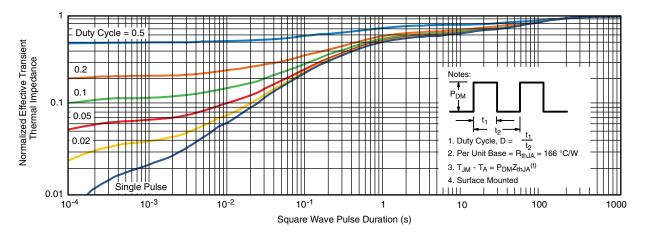


Power, Junction-to-Ambient

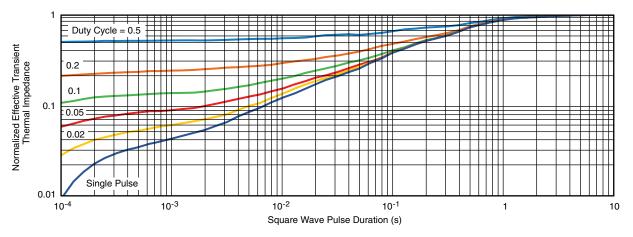
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?70132.



SOT-23 (TO-236): 3-LEAD







Dim	MILLIN	IETERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.90 BSC		0.074	8 Ref	
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		64 Ref 0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
ECN: S-03946-Rev. K. 09-	Jul-01				

DWG: 5479

Document Number: 71196 www.vishay.com 09-Jul-01



Recommended Minimum PADs for PowerPAK® 8 x 8L Single



Dimensions in millimeters (inches)

Note

· Linear dimensions are in black, the same information is provided in ordinate dimensions which are in blue.



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